

2-1-02

U.S. PATENT AND TRADEMARKS
Washington, D.C. 20231

Docket No. TS01-413

U.S. PTO
10/060483
01/30/02

Transmitted herewith for filing is the Patent Application of:

Inventor: YEN-MING CHEN, CHIA-FU LIN, SHUN LIANG HSU, KAI-MING CHING, HSIN-HUI LEE, CHAO-YUAN SU, LI-CHIH CHEN

For: NOVEL METHOD TO IMPROVE BUMP RELIABILITY FOR FLIP CHIP DEVICE

Enclosed are:

☒ 5 sheets of drawing(s) - formal.

☒ An assignment of the invention to Taiwan Semiconductor Manufacturing Company

☐ An associate power of attorney ☐ Applicant claims small entity status

☒ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 740.
TOTAL CLAIMS	28 -20=	8	x 18 =	\$ 144.
INDEP CLAIMS	2 -3=	0	x 84 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 884.
			ASSIGNMENT	\$40.
			TOTAL	\$ 924.

☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 924. A duplicate copy of this sheet is enclosed.

☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

☒ Any additional filing fees required under 37 CFR \$1.16.

☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

Express Mail Certificate

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231. Applicant and/or Attorney requests the date of deposit as the Filing Date.

1/30/02

Signature / Date

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

Yen-Ming Chen

Title

Novel Method To Improve Bump
Reliability For Flip Chip Device

Atty Docket Number

TS01-413

I hereby certify that the invention disclosed in the attached application **has not and will not** be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

1/30/02
Date



Signature

Stephen B. Ackerman, Reg. No. 37,761

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**